APPLICA	BLE STAN	DARD								
	OPERATING TEMPERATURE RANGE		00 0 10 100 0 (NOTE 1)			PRAGE -10°C TO +60°C (NOTE3)				)
RATING			20 % TO 80 % (NO		STORAGE HUMIDITY R	ANGE		20 % TO 70 %(NO		ГЕ3)
	VOLTAGE		150 V AC (DC)		CURRENT			1 A		
	APPLICABLE CONNECTOR		DE13-3S-1.25C		APPLICABLE CONTACT			DF13-2630SCFA(05) DF13-3032SCFA(05)		
	1		SPEC	IFICAT	IONS					
	EM		TEST METHOD			R	EQUIF	REMENTS	QT	АТ
CONSTR										
		VISUALLY AND BY MEASURING INSTRUMENT.  CONFIRMED VISUALLY.			ACCOF	ACCORDING TO DRAWING.				X
ELECTRIC CHARA										X
		100 m A (DC OR 1000 Hz).			30 mΩ	30 mΩ MAX.				Τ_
INSULATION		100 V DC.				500 MΩ MIN.				<u> </u>
RESISTANCE VOLTAGE PROOF		500 V AC FOR 1 min.			NO EL	AND ELABORATED OF PREAKEDOMAN			X	<u> </u>
WECHANICAL CHA					INO FLA	NO FLASHOVER OR BREAKDOWN. X				-
MECHANICA			ENISTICS INSERTIONS AND EXTRAC	CTIONS	(f) CO	NTACT RE	ESIST/	ANCE: 30 mO MAX		$\overline{}$
OPERATION		30 TIMES INSERTIONS AND EXTRACTIONS.			2 NO	<ul> <li>① CONTACT RESISTANCE: 30 mΩ MAX.</li> <li>② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.</li> </ul>				_
		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			② NO	1 NO ELECTRICAL DISCONTINUITY OF 1 µs. 2 NO DAMAGE, CRACK OR LOOSENESS OF			X	_
SHOCK		490 m/s <sup>2</sup> DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			S PAF	PARTS.				-
ENVIRONMENTAL RAPID CHANGE OF TEMPERATURE  DAMP HEAT (STEADY STATE)					min. ② INS ③ NO	<ul> <li>① CONTACT RESISTANCE: 30mΩ MAX.</li> <li>② INSULATION RESISTANCE: 500 MΩ MIN.</li> <li>③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.</li> </ul>			X	_
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING  «REFLOW AREA»  250°C MAX 10 sec MAX  230°C MIN 60 sec MAX  «PREHEATING AREA»  170°C TO 190°C 60 sec TO 120 sec  PUT THROUGH IN REFLOW FURNACE TWICE,  LEAVE IN AMBIENT TEMPERATURE AND  HUMIDITY FOR 1 HOUR.  2) MANUAL SOLDERING  SOLDERING IRON TEMPERATURE :350±10°C,  SOLDERING TIME : 5sec.  NO STRENGTH ON CONTACT.			LOOSE	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.				_
SOLDERABILITY		SOLDER	OLDERED AT SOLDER TEMPERATURE,			SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.				_
NOTE2:NO CO NOTE3:APPLY	ONDENSING Y TO THE CONI	ERATURE	FOR INSERTION DURATIO RISING BY CURRENT LONG TERM STORAGE FOR U IG TEMPERATURE AND HUMI	JNUSED PRO	DDUCTS BEFO	ORE PCB (	ON BOA	ARD,	X	I .TION.
. 1	T DE	SCRIPTION	ON OF REVISIONS	D	ESIGNED			CHECKED	DA	TE
COUNT	1			1		- 1				
COUNT						APPROV CHECK DESIGN	(ED NED	KI. AKIYAMA TS. KUMAZAWA KY. SHIMAKURA MI. SAKIMURA	13. 0 13. 0	2. 13 2. 13 2. 13 2. 07
	ualification Tes	st AT:Ass	urance Test X:Applicable Te	est	DRAWIN	CHECK DESIGN DRAW	(ED NED	TS. KUMAZAWA	13. 0 13. 0	2. 13
			urance Test X:Applicable Te		DRAWIN ART NO.	CHECK DESIGN DRAW	(ED	TS. KUMAZAWA KY. SHIMAKURA MI. SAKIMURA	13. 0 13. 0	12. 13 12. 13